Data Sheet April 1999 File Number 4013.2

16A, 30V, 0.025 Ohm, Logic Level, N-Channel Power MOSFETs

These are N-Channel power MOSFETs manufactured using the MegaFET process. This process, which uses feature sizes approaching those of LSI circuits, gives optimum utilization of silicon, resulting in outstanding performance. They were designed for use in applications such as switching regulators, switching converters, motor drivers and relay drivers. This performance is accomplished through a special gate oxide design which provides full rated conductance at gate bias in the 3V to 5V range, thereby facilitating true on-off power control directly from logic level (5V) integrated circuits.

Formerly developmental type TA49030.

Ordering InformationS

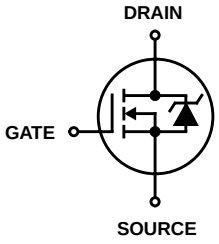
PART NUMBER	PACKAGE	BRAND
RFD16N03L	TO-251AA	16N03L
RFD16N03LSM	TO-252AA	16N03L

NOTE: When ordering, use the entire part number. Add the suffix 9A, to obtain the TO-252AA variant in tape and reel, e.g. RFD16N03LSM9A.

Features

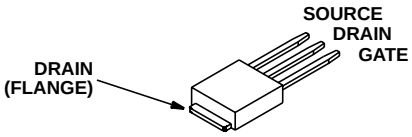
- 16A, 30V
- $r_{DS(ON)} = 0.025\Omega$
- Temperature Compensating PSPICE™ Model
- Can be Driven Directly from CMOS, NMOS, and TTL Circuits
- Peak Current vs Pulse Width Curve
- UIS Rating Curve
- $175^{o}C$ Operating Temperature
- Related Literature
  - TB334 “Guidelines for Soldering Surface Mount Components to PC Boards”

Symbol

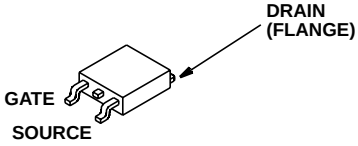


Packaging

JEDEC TO-251AA



JEDEC TO-252AA



Absolute Maximum Ratings $T_C = 25^oC$, Unless Otherwise Specified

		RFD16N03L, RFD16N03LSM	UNITS
Drain to Source Voltage	V_{DSS}	30	V
Drain to Gate Voltage (R_{GS} = 20kΩ) (Note 1)	V_{DGR}	30	V
Gate to Source Voltage	V_{GS}	±10	V
Continuous Drain Current (Figure 2)	I_D	16	A
Pulsed Drain Current	I_{DM}	Refer to Peak Current Curve	
Pulsed Avalanche Rating	E_{AS}	Figures 6, 16, 17	
Power Dissipation	P_D	90	W
Derate Above 25^oC (Figure 1)		0.606	$W/^oC$
Operating and Storage Temperature	T_J, T_{STG}	-55 to 175	^oC
Maximum Temperature for Soldering			
Leads at 0.063in (1.6mm) from Case for 10s	T_L	300	^oC
Package Body for 10s, See Techbrief 334	T_{pkg}	260	^oC

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

1. $T_J = 25^oC$ to 150^oC.

Electrical Specifications $T_C = 25^oC$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV_{DSS}	I_D = 250μA, V_{GS} = 0V (Figure 13)		30	-	-	V
Gate Threshold Voltage	$V_{GS(TH)}$	V_{GS} = V_{DS}, I_D = 250μA (Figure 12)		1	-	2	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 30V, V_{GS} = 0V	$T_C = 25^oC$	-	-	1	μA
			$T_C = 150^oC$	-	-	50	μA
Gate to Source Leakage Current	I_{GSS}	V_{GS} = ±10V		-	-	±100	nA
Drain to Source On Resistance	$r_{DS(ON)}$	I_D = 16A, V_{GS} = 5V (Figure 11)		-	-	0.025	Ω
Turn-On Time	t_{ON}	V_{DD} = 15V, $I_D \approx$ 16A, R_L = 0.93Ω, V_{GS} = 5V, R_{GS} = 5Ω (Figures 18, 19)		-	-	120	ns
Turn-On Delay Time	$t_{d(ON)}$			-	15	-	ns
Rise Time	t_r			-	95	-	ns
Turn-Off Delay Time	$t_{d(OFF)}$			-	25	-	ns
Fall Time	t_f			-	27	-	ns
Turn-Off Time	t_{OFF}			-	-	80	ns
Total Gate Charge	$Q_{g(TOT)}$	V_{GS} = 0V to 10V	V_{DD} = 24V, I_D = 16A, R_L = 1.5Ω $I_{G(REF)}$ = 0.6mA (Figures 15, 20, 21	-	50	60	nC
Gate Charge at 5V	$Q_{g(5)}$	V_{GS} = 0V to 5V		-	30	36	nC
Threshold Gate Charge	$Q_{g(TH)}$	V_{GS} = 0V to 1V		-	1.5	1.8	nC
Input Capacitance	C_{ISS}	V_{DS} = 25V, V_{GS} = 0V, f = 1MHz (Figure 14)		-	1650	-	pF
Output Capacitance	C_{OSS}			-	575	-	pF
Reverse Transfer Capacitance	C_{RSS}			-	200	-	pF
Thermal Resistance, Junction to Case	$R_{\theta JC}$	Figure 3		-	-	1.65	$^oC/W$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	TO-251 and TO-252		-	-	100	$^oC/W$

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	V_{SD}	I_{SD} = 16A	-	-	1.5	V
Diode Reverse Recovery Time	t_{rr}	I_{SD} = 16A, dI_{SD}/dt = 100A/μs	-	-	75	ns

NOTES:

2. Pulse Test: Pulse Width ≤ 300ms, Duty Cycle ≤ 2%.
3. Repetitive Rating: Pulse Width limited by max junction temperature. See Transient Thermal Impedance curve (Figure 3).

Typical Performance Curves Unless Otherwise Specified

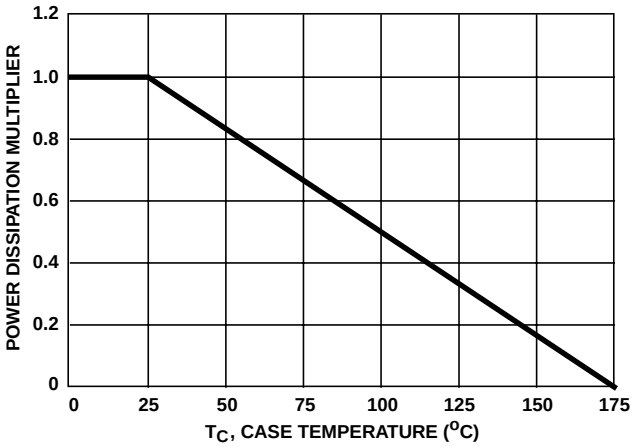


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

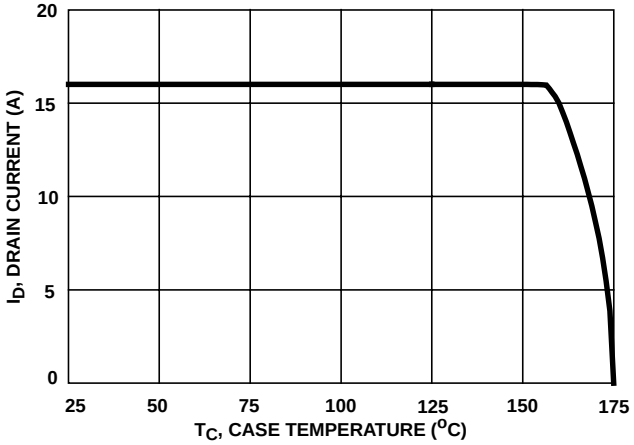


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

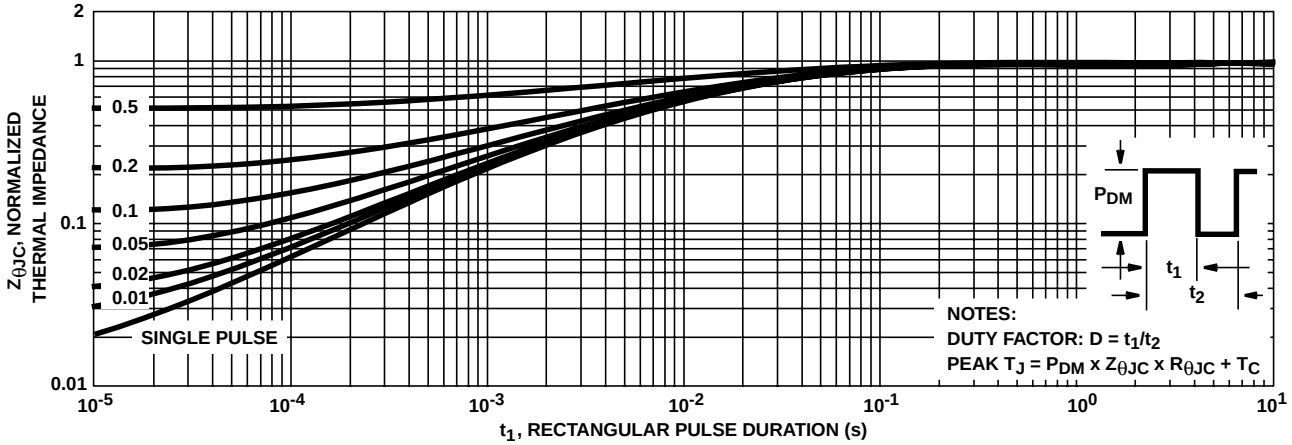


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

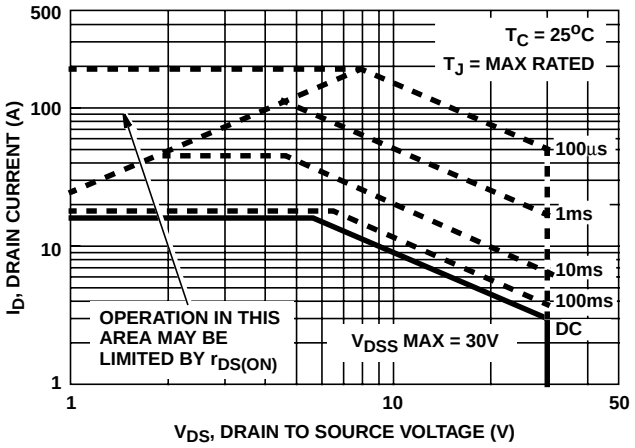


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

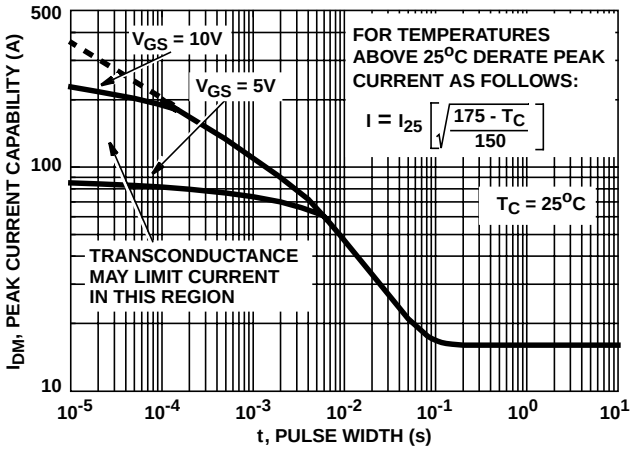
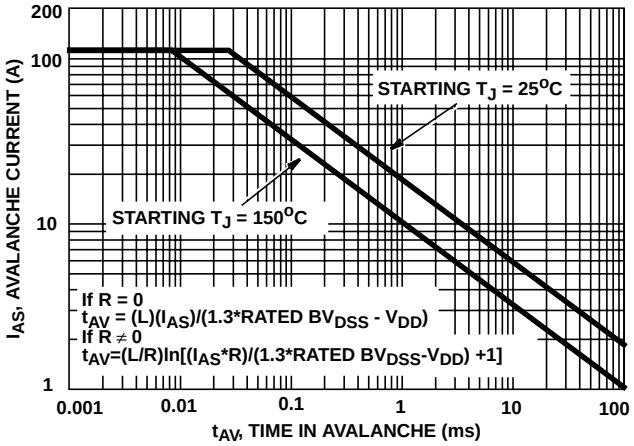


FIGURE 5. PEAK CURRENT CAPABILITY

Typical Performance Curves Unless Otherwise Specified (Continued)



NOTE: Refer to Intersil Application Notes AN9321 and AN9322.

FIGURE 6. UNCLAMPED INDUCTIVE SWITCHING

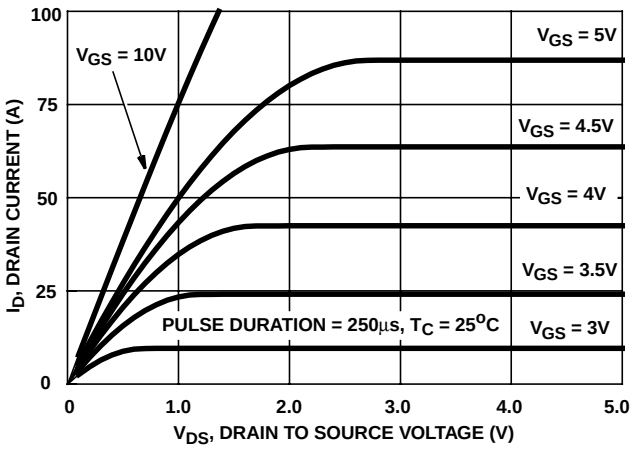


FIGURE 7. SATURATION CHARACTERISTICS

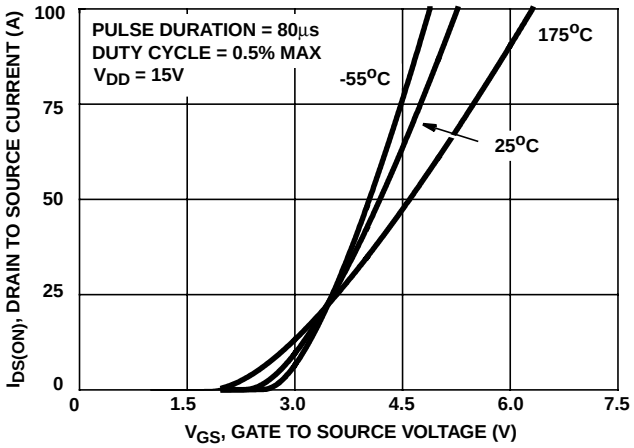


FIGURE 8. TRANSFER CHARACTERISTICS

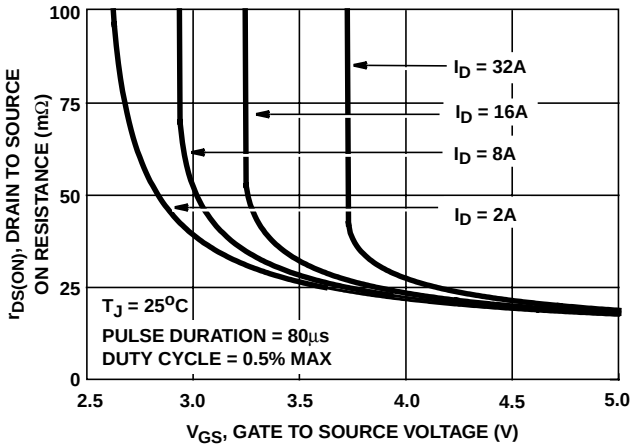


FIGURE 9. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

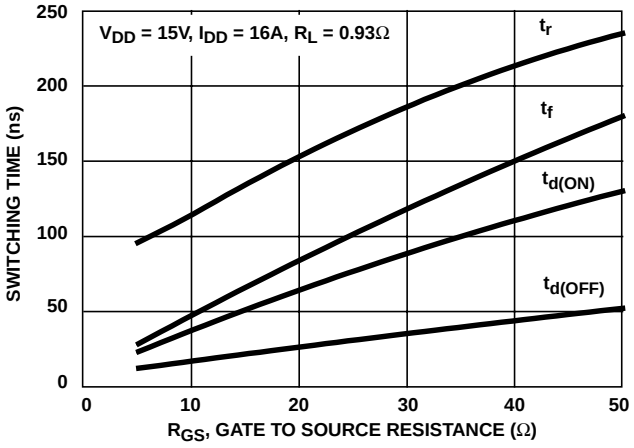


FIGURE 10. SWITCHING TIME vs GATE RESISTANCE

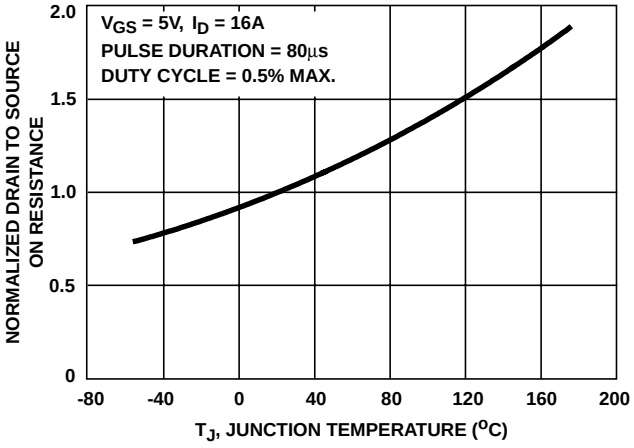


FIGURE 11. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

Typical Performance Curves Unless Otherwise Specified **(Continued)**

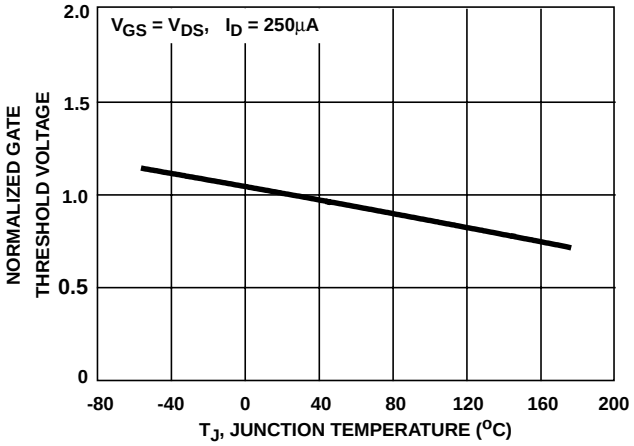


FIGURE 12. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

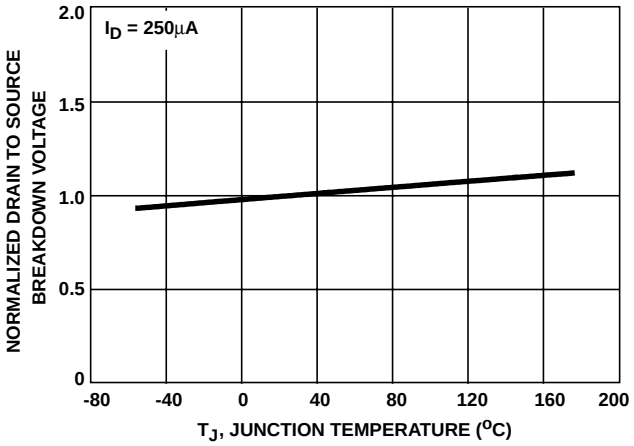


FIGURE 13. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

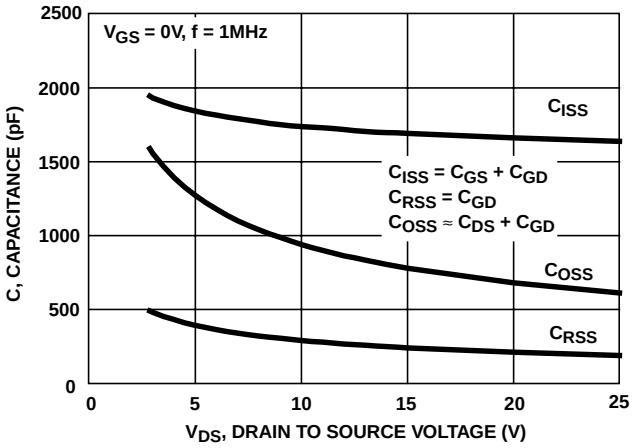
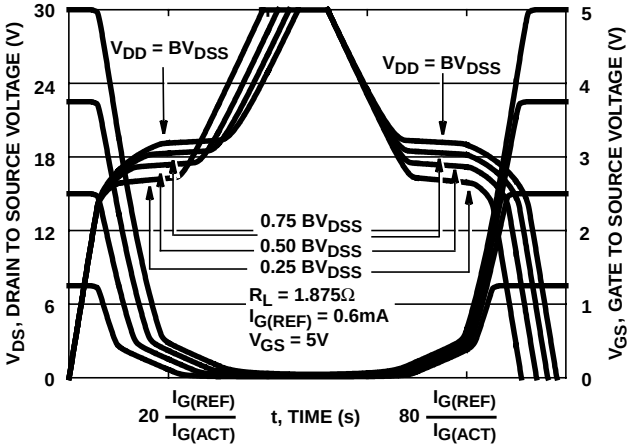


FIGURE 14. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Intersil Application Notes AN7254 and AN7260.

FIGURE 15. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms

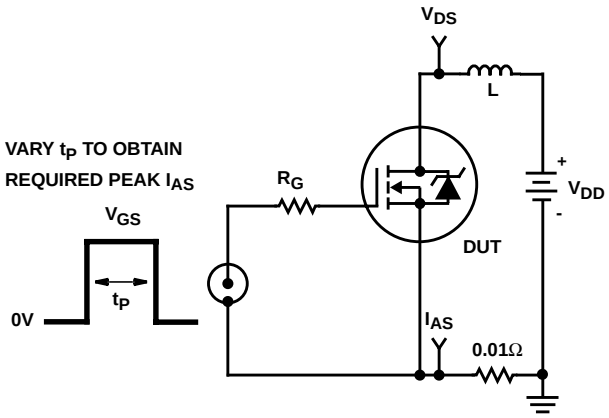


FIGURE 16. UNCLAMPED ENERGY TEST CIRCUIT

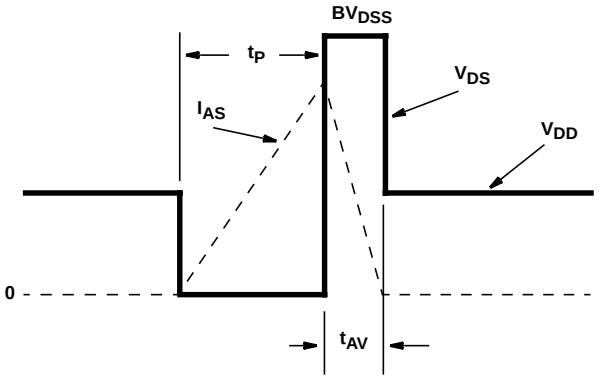


FIGURE 17. UNCLAMPED ENERGY WAVEFORMS

Test Circuits and Waveforms (Continued)

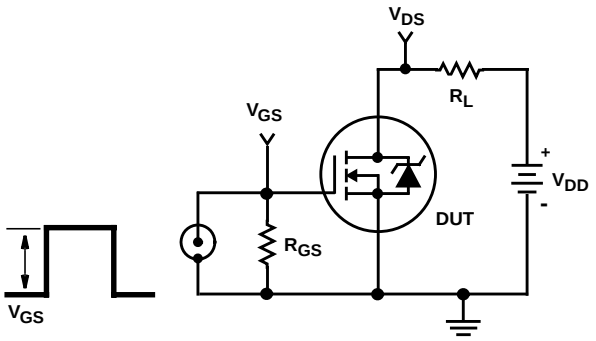


FIGURE 18. RESISTIVE SWITCHING TEST CIRCUIT

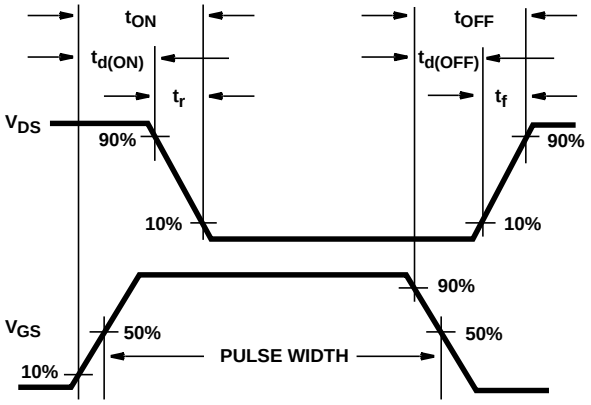


FIGURE 19. RESISTIVE SWITCHING WAVEFORMS

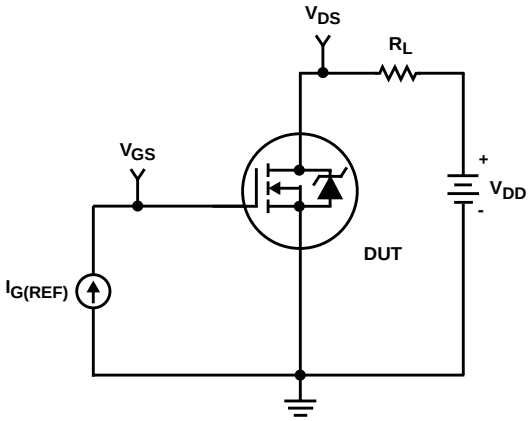


FIGURE 20. GATE CHARGE TEST CIRCUIT

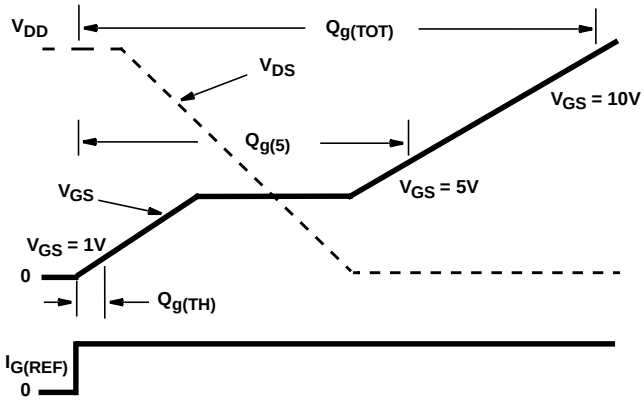
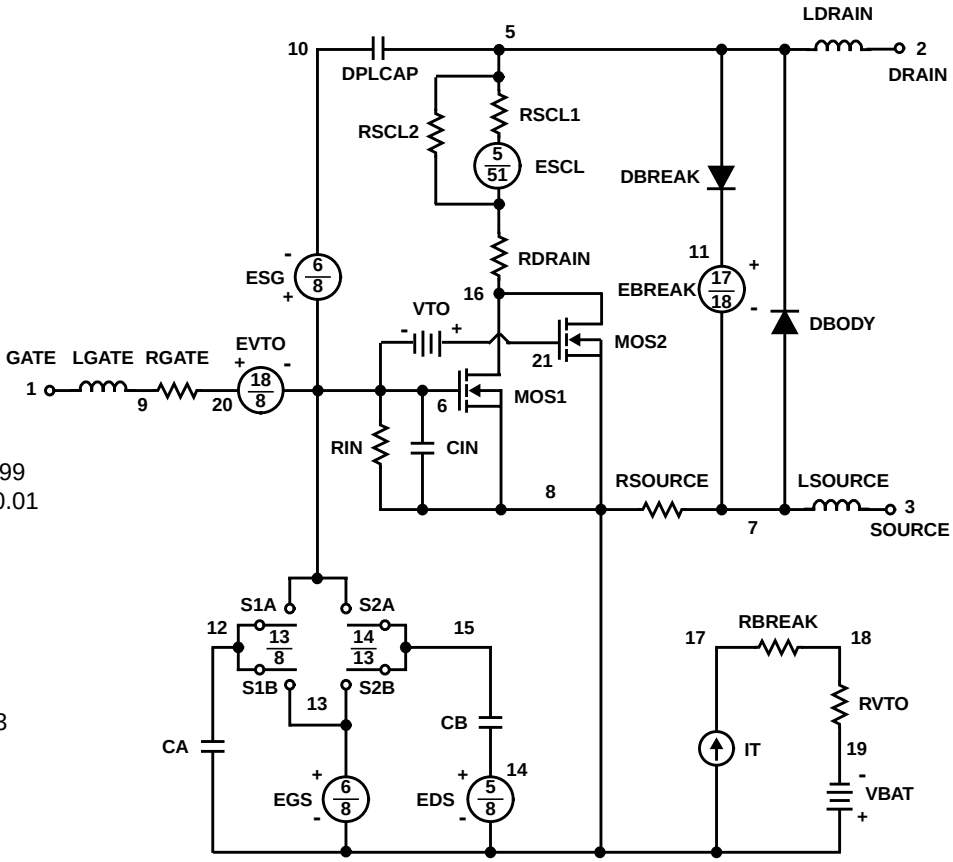


FIGURE 21. GATE CHARGE WAVEFORMS

PSPICE Electrical Model

```
.SUBCKT  RFD16N03L  2 1 3;       rev 12/12/94
CA  12  8  2.55e-9
CB  15  14  2.64e-9
CIN  6  8 1.45e-9

DBODY  7  5  DBDMOD
DBREAK  5 11  DBKMOD
DPLCAP 10  5  DPLCAPMOD

EBREAK  11  7  17  18  33.3

EDS  14  8  5  8  1
EGS  13  8  6  8  1
ESG  6  10  6  8  1
EVTO  20  6  18  8  1

IT  8  17  1

LDRAIN  2  5  1e-9
LGATE 1  9  3.4e-9
LSOURCE  3  7  3.4e-9

MOS1  16  6  8  8  MOSMOD  M = 0.99
MOS2  16  21  8  8  MOSMOD  M = 0.01

RBREAK  17  18  RBKMOD  1
RDRAIN  50  16  RDSMOD  0.14e-3
RGATE  9  20  0.89
RIN  6  8  1e9
RSCL1  5  51  RSCLMOD 1e-6
RSCL2  5  50  1e3
RSOURCE  8  7  RDSMOD  10.31e-3
RVTO  18  19  RVTOMOD  1

S1A  6  12  13  8  S1AMOD
S1B  13  12  13  8  S1BMOD
S2A  6  15  14  13  S2AMOD
S2B  13  15  14  13  S2BMOD

VBAT  8  19  DC  1
VTO  21  6  0.583
```




```
ESCL  51 50  VALUE = {(V(5,51)/ABS(V(5,51)))*(PWR(V(5,51)*1e6/176,6))}

.MODEL DBDMOD D (IS = 3.61e-13  RS = 5.06e-3  TRS1 = 3.05e-3  TRS2 = 7.57e-6  CJO = 2.16e-9  TT = 2.18e-8)
.MODEL DBKMOD D (RS = 1.66e-1  TRS1 = -2.97e-3  TRS2 = 7.57e-6)
.MODEL DPLCAPMOD D (CJO = 0.96e-9  IS = 1e-30  N = 10)
.MODEL MOSMOD NMOS (VTO = 2.313  KP = 53.82  IS = 1e-30  N = 10  TOX = 1  L = 1u  W = 1u)
.MODEL RBKMOD RES (TC1 = 8.95e-4  TC2 = -1e-7)
.MODEL RDSMOD RES (TC1 = 3.92e-3  TC2 = 1.29e-5)
.MODEL RSCLMOD RES (TC1 = 2.03e-3  TC2 = 0.45e-5)
.MODEL RVTOMOD RES (TC1 = -2.27e-3  TC2 = -5.75e-7)
.MODEL S1AMOD VSWITCH (RON = 1e-5  ROFF = 0.1  VON = -4.82  VOFF= -2.82)
.MODEL S1BMOD VSWITCH (RON = 1e-5  ROFF = 0.1  VON = -2.82  VOFF= -4.82)
.MODEL S2AMOD VSWITCH (RON = 1e-5  ROFF = 0.1  VON = -2.67  VOFF= 2.33)
.MODEL S2BMOD VSWITCH (RON = 1e-5  ROFF = 0.1  VON = 2.33  VOFF= -2.67)

.ENDS
```

NOTE: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; written by William J. Hepp and C. Frank Wheatley.

All Intersil semiconductor products are manufactured, assembled and tested under **ISO9000** quality systems certification.

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